

## METHOD FOR ISOLATING SELF-ALIGNED CONTACT PADS

### ABSTRACT OF THE DISCLOSURE

5 A method for isolating SAC pads of a semiconductor device, including  
determining a chemical mechanical polishing process time necessary to isolate  
the SAC pads a desired amount by referring to a relationship equation between  
the extent of isolation of the self-aligned contact pads and the  
chemical-mechanical polishing process time. The chemical mechanical  
polishing process is performed for the determined process time on the  
10 semiconductor device to isolate the self-aligned contact pads the desired amount.  
The relationship equation is determined using a test semiconductor device.